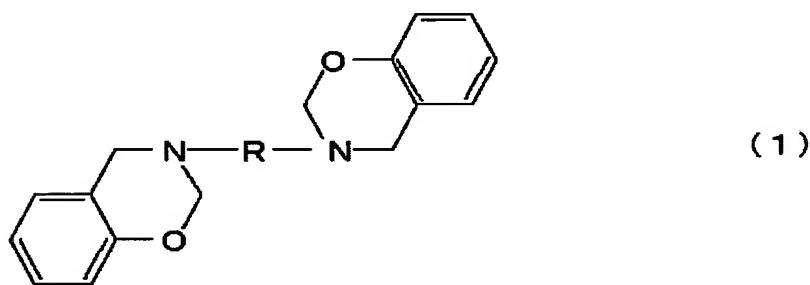


ABSTRACT OF THE DISCLOSURE

The invention provides a thermosetting resin composition comprising a bifunctional dihydrobenzoxazine compound and an epoxy compound, and provides a thermosetting resin molding obtained by thermally curing the thermosetting resin composition. The molding has excellent electric properties of low dielectric constant and low dielectric loss tangent. The resin composition comprises an epoxy compound and a bifunctional dihydrobenzoxazine compound of the following general formula (1), wherein the equivalent ratio of the epoxy compound to the bifunctional dihydrobenzoxazine compound is 1/(0.1 to 20):



wherein R represents a linear alkylene group having at least 2 carbon atoms, or a branched alkylene group derived from it by substituting the hydrogen atom therein with an alkyl group, and the hydrogen atom of the benzene ring may be substituted with an alkyl group or an alkoxy group.